



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



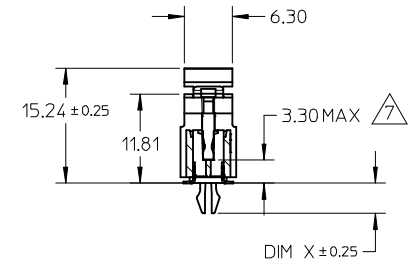
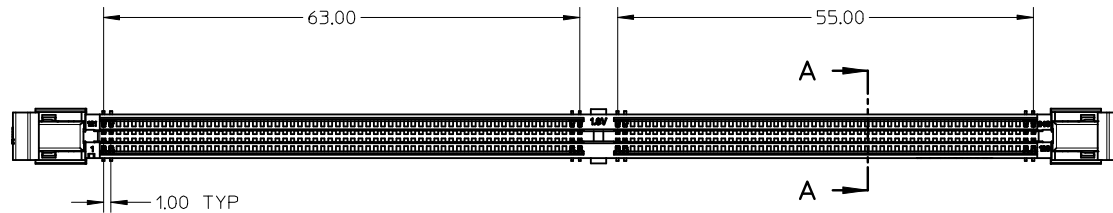
Contact us

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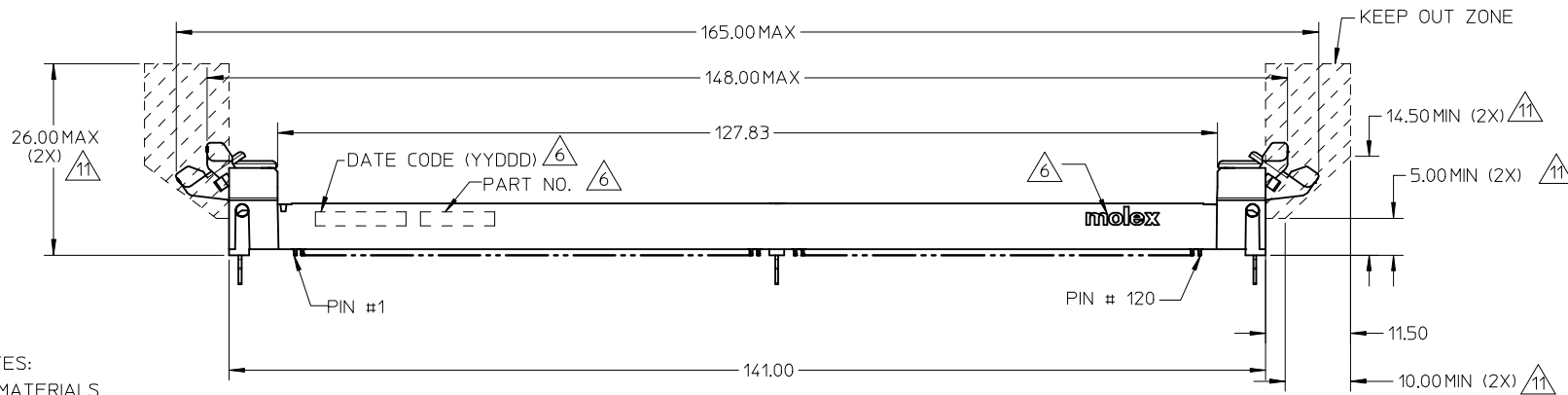
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





SECTION A-A



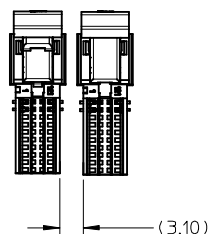
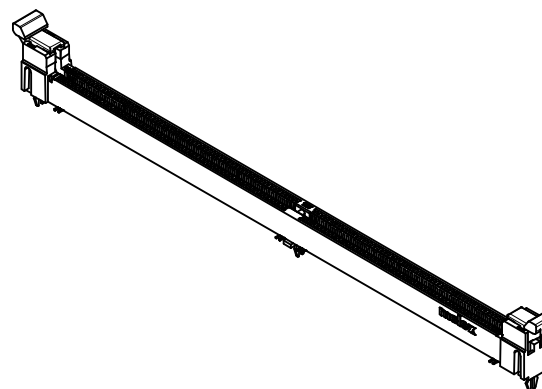
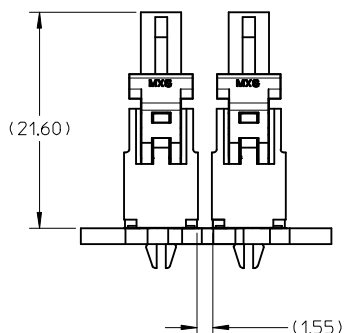
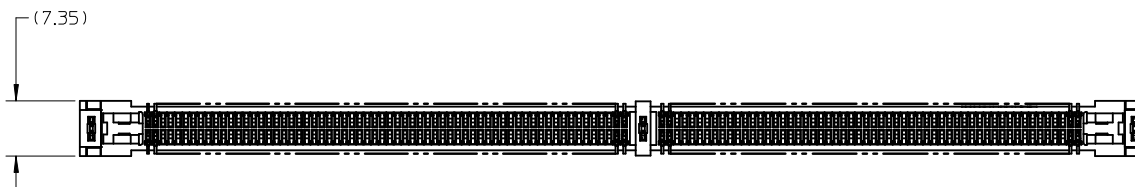
NOTES:

1. MATERIALS
HOUSING - LCP, GLASS FILLED, UL 94V-0. BLACK
EJECTORS - HIGH TEMP. NYLON GLASS FILLED, UL 94 V-0,
COLOUR - PLS REFER TO SHEET 2.
TERMINALS - COPPER ALLOY
2. PLATING OPTION - PLS REFER TO SHEET 2.
3. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS. (MEASURED OVER PC PADS)
4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC M0-237. PLS REFER TO SHEET 3.
5. PRODUCT IS PACKED INTO TRAYS. PLS REFER TO SHEET 5
6. MOLEX LOGO, DATE CODE & PART NO. INDICATED ON HOUSING.
7. DIMM MODULE SEATING PLANE FROM TOP OF PCB.
8. COPLANARITY OF SOLDER TAILS SHALL NOT EXCEED 0.20MM.
9. REFER TO PRODUCT SPEC. PS-78125-001 FOR PERFORMANCE SPECIFICATIONS.
10. THE KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB, WHICH DOES NOT INCLUDE THE LATCH.
11. KEEP OUT ZONE AS PER JEDEC SO-001.
12. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

ADD NEW OPTION EC NO: S2009-0166 DRWN:CMTEO 2008/09/05 CHKD:CGTAN 2008/09/05 APPR:SHLENI 2008/09/05	B1 REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY CMTEO	DATE 2006/08/07	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS, VLP LATCH, SMT			
			4 PLACES	± ---	± ---	CHECKED BY SHLENI	DATE 2006/08/14	MOLEX INCORPORATED DOCUMENT NO. SD-78125-001 SHEET NO. 1 OF 5			
			3 PLACES	± ---	± ---	APPROVED BY GGLEE	DATE 2006/08/14				
2 PLACES	± 0.2	± ---	MATERIAL NO.		SEE TABLE						
1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			ANGULAR ± 1 °								

10 9 8 7 6 5 4 3 2 1

ASSEMBLY PART NO.	VOLTAGE KEY POS.	DIM X	PCB THICKNESS DIM Y	PLATING	LATCH COLOR
78125-0001	CENTRE 1.8V	3.94	1.57	0.76µM (30µ IN) MIN. GOLD ON CONTACT 2.54µM (100µ IN) MIN. TIN ON SOLDER TAILS 1.27µM (50µ IN) MIN. NICKEL UNDERPLATE	BLACK
78125-0008		4.42	2.50		

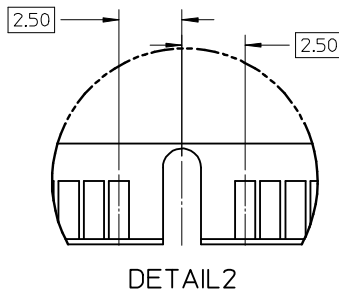
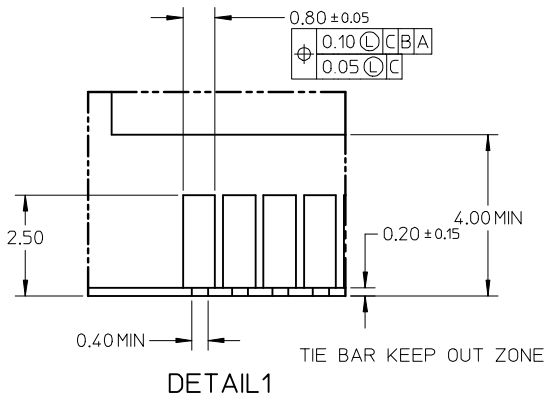
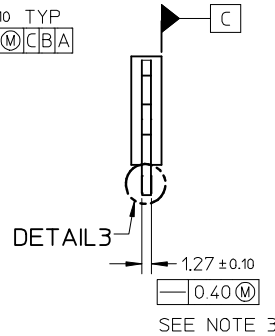
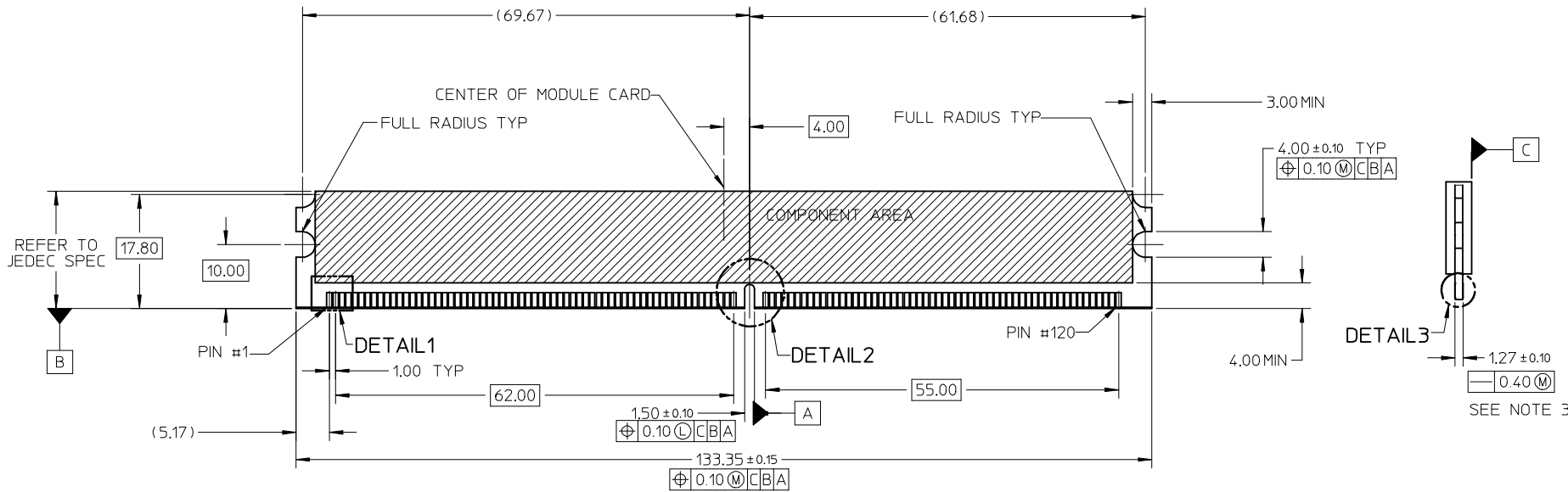


ADD NEW OPTION EC NO: S2009-0166 DRWN:CMTEO CHKD:CGTAN APPR:SHLENI	2008/09/05 2008/09/05 2008/09/05	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
					mm	INCH	DRAWN BY	DATE	TITLE					
				4 PLACES	± ---	± ---	CMTEO	2006/08/07	DDR2 DIMM, 100MM PITCH 240 CKTS, VLP LATCH, SMT					
				3 PLACES	± ---	± ---	CHECKED BY	DATE	MOLEX INCORPORATED					
	± 0.2	± ---	SHLENI	2006/08/14	APPROVED BY									
2 PLACES	± ---	± ---	GGLEE	2006/08/14	MATERIAL NO.									
1 PLACE	± ---	± ---	ANGULAR ± 1 °			SEE TABLE			DOCUMENT NO.					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								
B1				A3		SD-78125-001			SHEET NO. 2 OF 5					

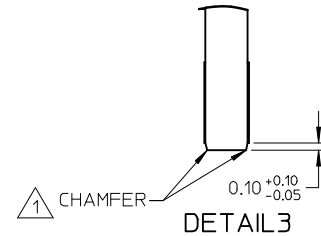
9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

RECOMMENDED MODULE LAYOUT



KEY LOCATION	VOLTAGE
CENTER	1.8V

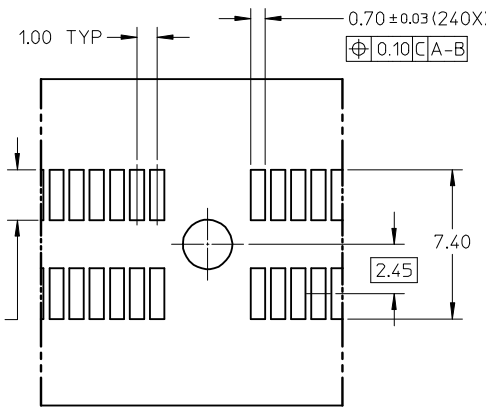
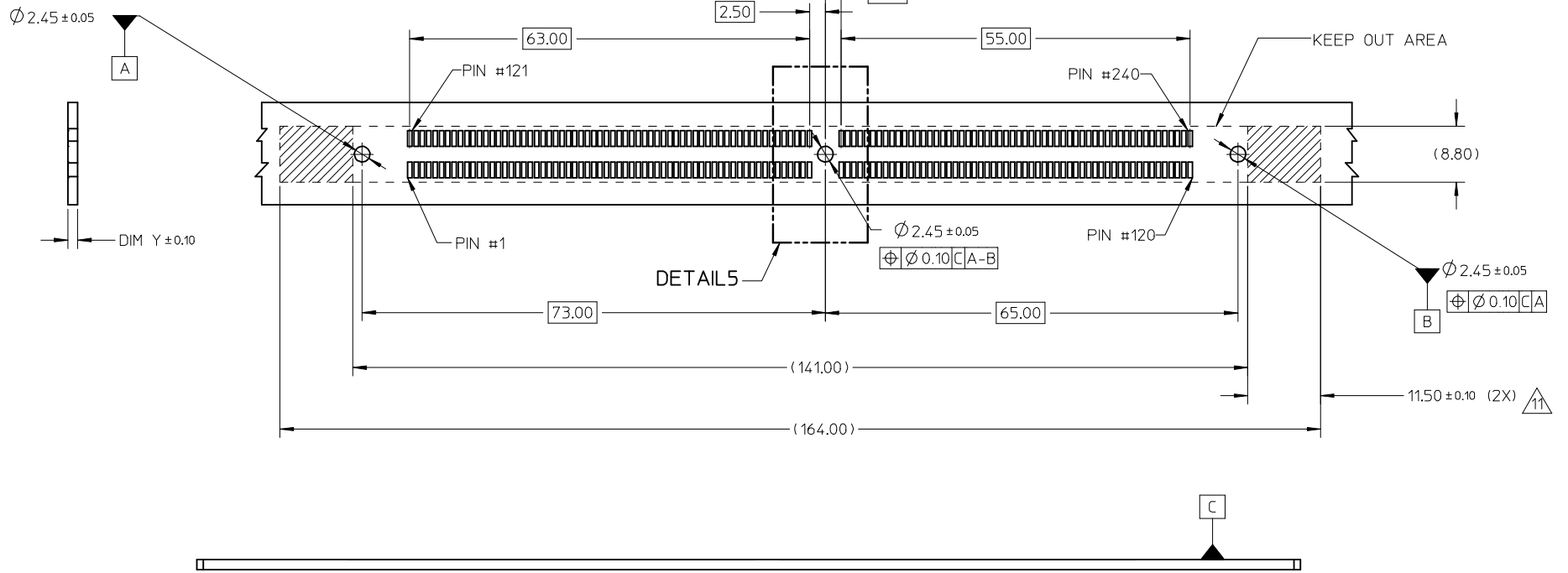


NOTES:
 1. MODULE CARD USED FOR TESTS ARE WITH 0.10MM CHAMFER.

ADD NEW OPTION EC NO: S2009-0166 DRWN:CMTEO 2008/09/05 CHKD:CGTAN 2008/09/05 APPR:SHLENI 2008/09/05	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DIMENSION STYLE MM ONLY DRAWN BY: CMTEO DATE: 2006/08/07 CHECKED BY: SHLENI DATE: 2006/08/14 APPROVED BY: GGLEE DATE: 2006/08/14	SCALE: NTS DESIGN UNITS: METRIC THIRD ANGLE PROJECTION	TITLE: DDR2 DIMM, 100MM PITCH 240 CKTS, VLP LATCH, SMT
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.: SEE TABLE DOCUMENT NO.: SD-78125-001 SHEET NO.: 3 OF 5	MOLEX INCORPORATED		
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
	B1	REV			

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



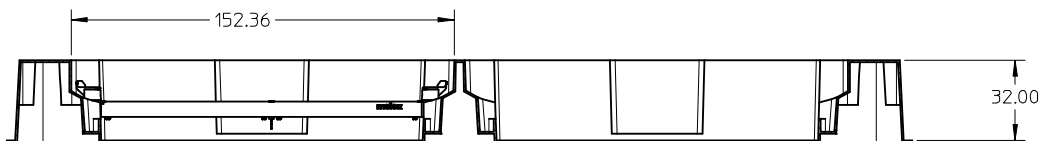
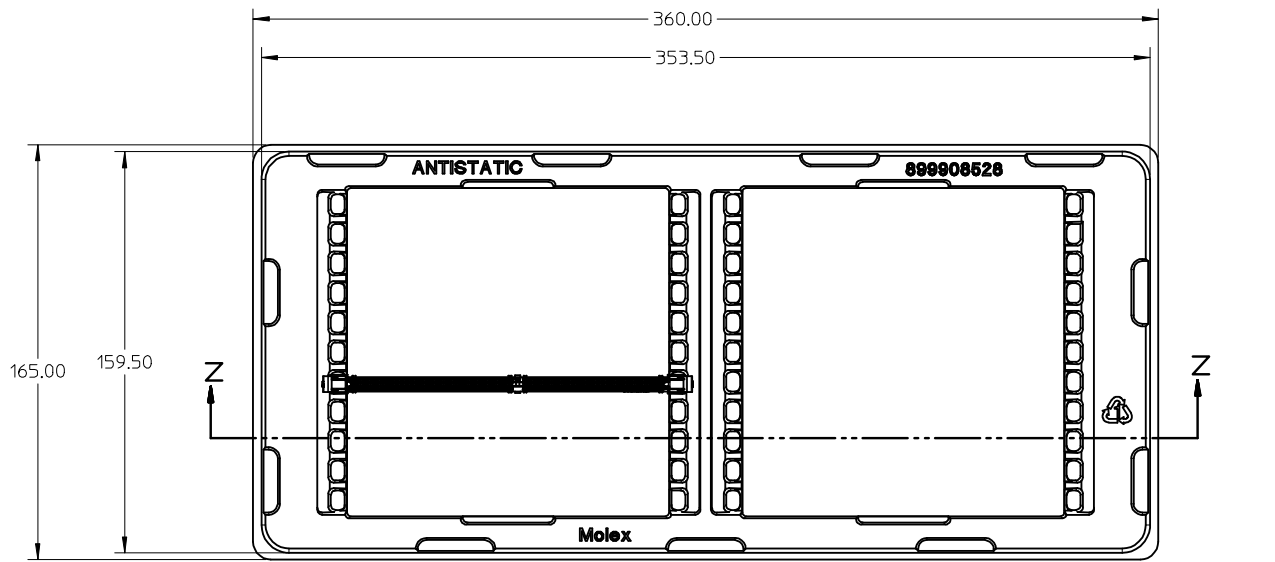
RECOMMENDED STENCIL THICKNESS = 150µM.

2.50 ± 0.03 (240X)
 $\oplus 0.10 [C-A-B]$

DETAIL5

ADD NEW OPTION EC NO: S2009-0166 DRWN:CMTEO 2008/09/05 CHKD:CGTAN 2008/09/05 APPR:SHLENI 2008/09/05	QUALITY SYMBOLS $\nabla=0$ $\nabla=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY CMTEO	DATE 2006/08/07	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS, VLP LATCH, SMT			
		3 PLACES ± --- ± ---		CHECKED BY SHLENI	DATE 2006/08/14	MOLEX INCORPORATED			
		2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± ---		APPROVED BY GGLEE	DATE 2006/08/14	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78125-001	SHEET NO. 4 OF 5	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1



SECTION Z-Z

NOTE:
1. CAVITY QTY : 2 X 11 = 22PCS

ADD NEW OPTION EC NO: S2009-0166 DRW:CMTEO 2008/09/05 CHKD:CGTAN 2008/09/05 APPR:SHLENI 2008/09/05	DESCRIPTION B1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		$\nabla=0$ $\square=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	MM ONLY	NTS	METRIC		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE CMTEO 2006/08/07 CHECKED BY DATE SHLENI 2006/08/14 APPROVED BY DATE GGLEE 2006/08/14 MATERIAL NO.	TITLE	DDR2 DIMM, 100MM PITCH 240 CKTS, VLP LATCH, SMT		
				SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-78125-001			SHEET NO. 5 OF 5